

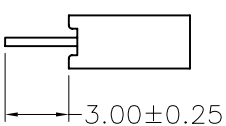
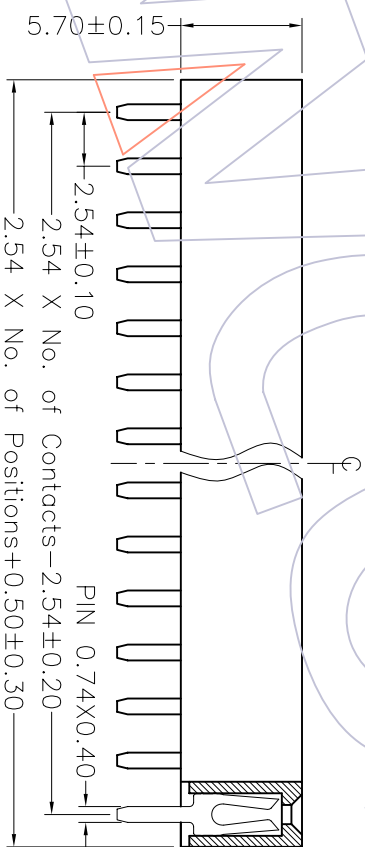
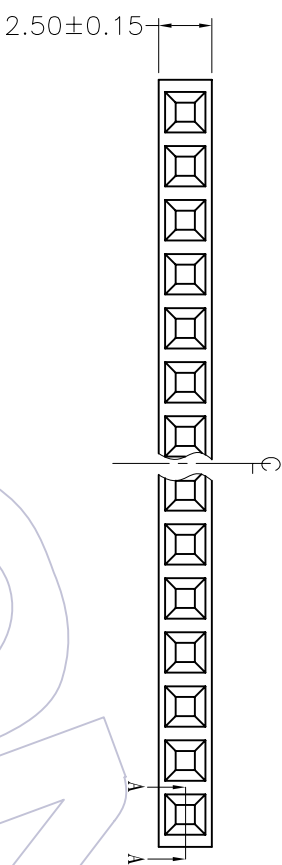
HSP

NOTES:

Current Rating: 3.0AMP
 Withstand Voltage: 500V AC/DC
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩMin
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze or Brass
 Contact plating: Au or Sn over Ni
 Insulator Material: PA6T or PBT+30%G.F UL94V-0

Recommended P.C.B Layout(TOP Side)
 (PCB BOARD TOLERANCE±0.05)



Ordering Information

2157-1XX SXX XYN A1

No. of Pins per ROW: 02-40PIN
 Contact Plating: GO=Gold Flash, GI=3μ"Gold, GS=5μ"Gold, GA=15μ"Gold, GP=30μ"Gold
 Insulator: A=PBT, C=PA6T
 Packing: A=Tray, T=Tube
 SO=Gold Flash/Tin, SI=3μ"Gold/Tin, S2=5μ"Gold/Tin, S3=10μ"Gold/Tin, S4=15μ"Gold/Tin, S5=30μ"Gold/Tin, SN=Tin

SECTION: A-A

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	SCALE	PART NO.	TITLE:
A0	08/03/01	NEW			XXX ±0.40 XXX ±0.25 X.XXX ±0.15 Angle ± .3'	DESIGN CHECK		4:1 mm A4	2157-1XXSXXYYNA1	FH2.54 SINGLE 180° H=5.7
1					DIM	APPROVE		PROJ.	Customer NO.	

WCON 维峰五金电子有限公司
 WAFER HARDWARE ELECTRONICS CO.,LTD